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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc716t-04i-ss

TABLE 1-1: PIC16C712/716 PINOUT DESCRIPTION (CONTINUED)

Pin Name	PIC16C712/716 DIP, SOIC	PIC16C712/716 SSOP	Pin Type	Buffer Type	Description
					PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT	6	7			
RB0			I/O	TTL	Digital I/O
INT			I	ST	External Interrupt
RB1/T1OSO/T1CKI	7	8			
RB1			I/O	TTL	Digital I/O
T1OSO			O	—	Timer1 oscillator output. Connects to crystal in oscillator mode.
T1CKI			I	ST	Timer1 external clock input.
RB2/T1OSI	8	9			
RB2			I/O	TTL	Digital I/O
T1OSI			I	—	Timer1 oscillator input. Connects to crystal in oscillator mode.
RB3/CCP1	9	10			
RB3			I/O	TTL	Digital I/O
CCP1			I/O	ST	Capture1 input, Compare1 output, PWM1 output.
RB4	10	12	I/O	TTL	Digital I/O Interrupt on change pin.
RB5	11	12	I/O	TTL	Digital I/O Interrupt on change pin.
RB6	12	13	I/O	TTL	Digital I/O Interrupt on change pin.
			I	ST	ICSP programming clock.
RB7	13	14	I/O	TTL	Digital I/O Interrupt on change pin.
			I/O	ST	ICSP programming data.
VSS	5	5, 6	P	—	Ground reference for logic and I/O pins.
VDD	14	15, 16	P	—	Positive supply for logic and I/O pins.

Legend: TTL = TTL-compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
OD = Open drain output
SM = SMBus compatible input. An external resistor is required if this pin is used as an output
NPU = N-channel pull-up PU = Weak internal pull-up
No-P diode = No P-diode to VDD AN = Analog input or output
I = input O = output
P = Power L = LCD Driver

2.2.2.2 OPTION_REG Register

The OPTION_REG register is a readable and writable register, which contains various control bits to configure the TMR0 prescaler/WDT postscaler (single assignable register known also as the prescaler), the External INT Interrupt, TMR0 and the weak pull-ups on PORTB.

Note:	To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer.

FIGURE 2-5: OPTION_REG REGISTER (ADDRESS 81h)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR Reset

bit 7: **$\overline{\text{RBPU}}$**: PORTB Pull-up Enable bit
1 = PORTB pull-ups are disabled
0 = PORTB pull-ups are enabled by individual port latch values

bit 6: **INTEDG**: Interrupt Edge Select bit
1 = Interrupt on rising edge of RB0/INT pin
0 = Interrupt on falling edge of RB0/INT pin

bit 5: **T0CS**: TMR0 Clock Source Select bit
1 = Transition on RA4/T0CKI pin
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: TMR0 Source Edge Select bit
1 = Increment on high-to-low transition on RA4/T0CKI pin
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit
1 = Prescaler is assigned to the WDT
0 = Prescaler is assigned to the Timer0 module

bit 2-0: **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

3.0 I/O PORTS

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

Additional information on I/O ports may be found in the PIC® Mid-Range Reference Manual, (DS33023).

3.1 PORTA and the TRISA Register

PORTA is a 5-bit wide bidirectional port. The corresponding data direction register is TRISA. Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input, (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output, (i.e., put the contents of the output latch on the selected pin).

Reading the PORTA register reads the status of the pins whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, the value is modified, and then written to the port data latch.

Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin. The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other RA port pins have TTL input levels and full CMOS output drivers.

PORTA pins, RA3:0, are multiplexed with analog inputs and analog V_{REF} input. The operation of each pin is selected by clearing/setting the control bits in the ADCON1 register (A/D Control Register1).

> **Note:** On a Power-on Reset, these pins are configured as analog inputs and read as '0'.

The TRISA register controls the direction of the RA pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set when using them as analog inputs.

EXAMPLE 3-1: INITIALIZING PORTA

```
BCF     STATUS, RP0  ;
CLRF    PORTA        ; Initialize PORTA by
                     ; clearing output
                     ; data latches
BSF     STATUS, RP0  ; Select Bank 1
MOVLW   0xEF         ; Value used to
                     ; initialize data
                     ; direction
MOVWF   TRISA        ; Set RA<3:0> as inputs
                     ; RA<4> as outputs
BCF     STATUS, RP0  ; Return to Bank 0
```

TABLE 3-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111
81h	OPTION_REG	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged. Shaded cells are not used by PORTB.

NOTES:

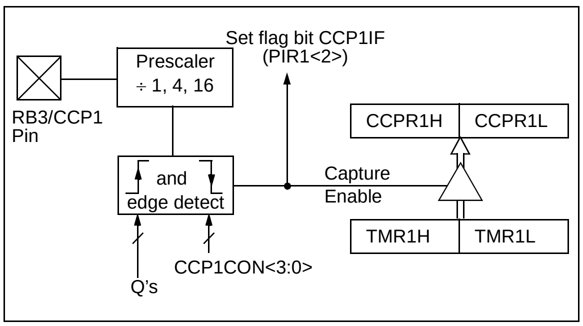
7.1 Capture Mode

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RB3/CCP1. An event is defined as:

- every falling edge
- every rising edge
- every 4th rising edge
- every 16th rising edge

An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

FIGURE 7-3: CAPTURE MODE OPERATION BLOCK DIAGRAM



7.1.1 CCP PIN CONFIGURATION

In Capture mode, the CCP output must be disabled by setting the TRISCCP<2> bit.

Note:	If the RB3/CCP1 is configured as an output by clearing the TRISCCP<2> bit, a write to the DCCP bit can cause a capture condition.

7.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work.

7.1.3 SOFTWARE INTERRUPT

When the Capture mode is changed, a false capture interrupt may be generated. The user should keep bit CCP1IE (PIE1<2>) clear to avoid false interrupts and should clear the flag bit CCP1IF following any such change in Operating mode.

7.1.4 CCP PRESCALER

There are four prescaler settings, specified by bits CCP1M3:CCP1M0. Whenever the CCP module is turned off, or the CCP module is not in Capture mode, the prescaler counter is cleared. This means that any Reset will clear the prescaler counter.

Switching from one capture prescaler to another may generate an interrupt. Also, the prescaler counter will not be cleared, therefore the first capture may be from a non-zero prescaler. Example 7-1 shows the recommended method for switching between capture prescalers. This example also clears the prescaler counter and will not generate the “false” interrupt.

EXAMPLE 7-1: CHANGING BETWEEN CAPTURE PRESCALERS

```
CLRF    CCP1CON       ;Turn CCP module off
MOVLW   NEW_CAPT_PS   ;Load the W reg with
                      ; the new prescaler
                      ; mode value and CCP ON
MOVWF   CCP1CON       ;Load CCP1CON with this

                      ; value
```

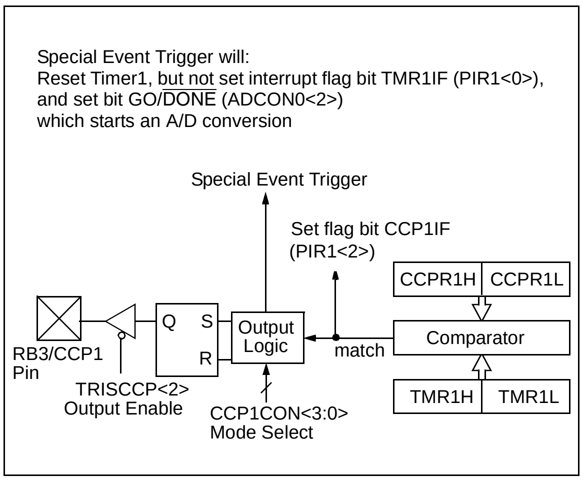
7.2 Compare Mode

In Compare mode, the 16-bit CCPR1 register value is constantly compared against the TMR1 register pair value. When a match occurs, the RB3/CCP1 pin is either:

- driven High
- driven Low
- remains Unchanged

The action on the pin is based on the value of control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). At the same time, interrupt flag bit CCP1IF is set.

FIGURE 7-4: COMPARE MODE OPERATION BLOCK DIAGRAM



7.2.1 CCP PIN CONFIGURATION

The user must configure the RB3/CCP1 pin as the CCP output by clearing the TRISCCP<2> bit.

Note:	Clearing the CCP1CON register will force the RB3/CCP1 compare output latch to the default low level. This is neither the PORTB I/O data latch nor the DATACCP latch.

7.2.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

7.2.3 SOFTWARE INTERRUPT MODE

When generate software interrupt is chosen the CCP1 pin is not affected. Only a CCP interrupt is generated (if enabled).

7.2.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated which may be used to initiate an action.

The Special Event Trigger output of CCP1 resets the TMR1 register pair. This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

The Special Event Trigger output of CCP1 also starts an A/D conversion (if the A/D module is enabled).

Note:	The Special Event Trigger from the CCP1 module will not set interrupt flag bit TMR1IF (PIR1<0>).

TABLE 7-2: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, AND TIMER1

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
07h	DATACCP	—	—	—	—	—	DCCP	—	DT1CK	xxxx xxxx	xxxx xuxu
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	—	CCP1IF	TMR2IF	TMR1IF	-0-- -000	-0-- -000
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
15h	CCPR1L	Capture/Compare/PWM Register 1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM Register 1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
87h	TRISCCP	—	—	—	—	—	TCCP	—	TT1CK	xxxx x1x1	xxxx x1x1
8Ch	PIE1	—	ADIE	—	—	—	CCP1IE	TMR2IE	TMR1IE	-0-- -000	-0-- -000

Legend: x = unknown, u = unchanged, — = unimplemented read as '0'. Shaded cells are not used by Capture and Timer1.

7.3 PWM Mode

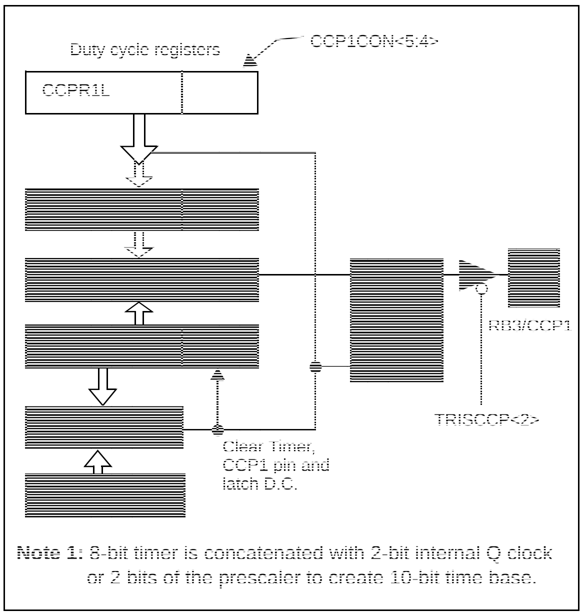
In Pulse Width Modulation (PWM) mode, the CCP1 pin produces up to a 10-bit resolution PWM output. Since the CCP1 pin is multiplexed with the PORTB data latch, the TRISCCP<2> bit must be cleared to make the CCP1 pin an output.

> **Note:** Clearing the CCP1CON register will force the CCP1 PWM output latch to the default low level. This is neither the PORTB I/O data latch nor the DATACCP latch.

Figure 7-5 shows a simplified block diagram of the CCP module in PWM mode.

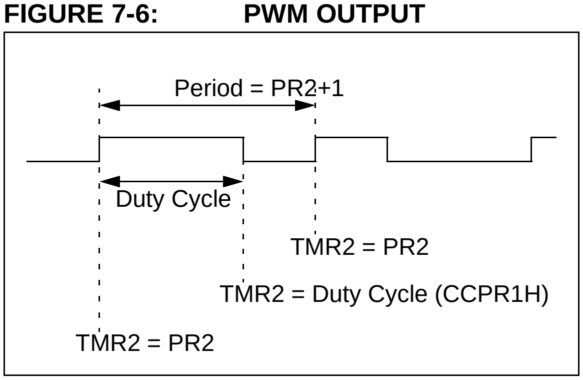
For a step by step procedure on how to set up the CCP module for PWM operation, see **Section 7.3.3 "Set-Up for PWM Operation"**.

FIGURE 7-5: SIMPLIFIED PWM BLOCK DIAGRAM



A PWM output (Figure 7-6) has a time base (period) and a time that the output stays high (duty cycle). The frequency of the PWM is the inverse of the period (1/period).

FIGURE 7-6: PWM OUTPUT



7.3.1 PWM PERIOD

The PWM period is specified by writing to the PR2 register. The PWM period can be calculated using the following formula:

$$\textbf{PWM period} = [(PR2) + 1] \cdot 4 \cdot T_{OSC} \cdot (\text{TMR2 prescale value})$$

PWM frequency is defined as 1 / [PWM period].

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The CCP1 pin is set (exception: if PWM duty cycle = 0%, the CCP1 pin will not be set)
- The PWM duty cycle is latched from CCPR1L into CCPR1H

> **Note:** The Timer2 postscaler (see **Section 6.0 "Timer2 Module"**) is not used in the determination of the PWM frequency. The postscaler could be used to have a servo update rate at a different frequency than the PWM output.

7.3.2 PWM DUTY CYCLE

The PWM duty cycle is specified by writing to the CCPR1L register and to the CCP1CON<5:4> bits. Up to 10-bit resolution is available. The CCPR1L contains the eight MSbs and the CCP1CON<5:4> contains the two LSbs. This 10-bit value is represented by CCPR1L:CCP1CON<5:4>. The following equation is used to calculate the PWM duty cycle in time:

$$\textbf{PWM duty cycle} = (CCPR1L{:}CCP1CON<5:4>) \cdot T_{OSC} \cdot (\text{TMR2 prescale value})$$

CCPR1L and CCP1CON<5:4> can be written to at any time, but the duty cycle value is not latched into CCPR1H until after a match between PR2 and TMR2 occurs (i.e., the period is complete). In PWM mode, CCPR1H is a read-only register.

The CCPR1H register and a 2-bit internal latch are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

When the CCPR1H and 2-bit latch match TMR2 concatenated with an internal 2-bit Q clock or 2 bits of the TMR2 prescaler, the CCP1 pin is cleared.

Maximum PWM resolution (bits) for a given PWM frequency:

$$= \frac{\log\left(\frac{F_{OSC}}{F_{PWM}}\right)}{\log(2)} \text{ bits}$$

> **Note:** If the PWM duty cycle value is longer than the PWM period the CCP1 pin will not be cleared.

For an example PWM period and duty cycle calculation, see the PIC® Mid-Range Reference Manual, (DS33023).

8.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has four inputs.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's positive supply voltage (VDD) or the voltage level on the RA3/AN3/VREF pin.

The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

Additional information on the A/D module is available in the PIC® Mid-Range Reference Manual, (DS33023).

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The ADCON0 register, shown in Figure 8-1, controls the operation of the A/D module. The ADCON1 register, shown in Figure 8-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/O.

FIGURE 8-1: ADCON0 REGISTER (ADDRESS 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	$\overline{\text{ADON}}$
bit7							bit0

R =	Readable bit
W =	Writable bit
U =	Unimplemented bit, read as '0'
-n =	Value at POR Reset

bit 7-6: **ADCS1:ADCS0:** A/D Conversion Clock Select bits
00 = FOSC/2
01 = FOSC/8
10 = FOSC/32
11 = FRC (clock derived from the internal ADC RC oscillator)

bit 5-3: **CHS2:CHS0**: Analog Channel Select bits
000 = channel 0, (RA0/AN0)
001 = channel 1, (RA1/AN1)
010 = channel 2, (RA2/AN2)
011 = channel 3, (RA3/AN3)
1xx = reserved, do not use

bit 2: **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

If ADON = 1
1 = A/D conversion in progress (setting this bit starts the A/D conversion)
0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1: **Unimplemented**: Read as '0'

bit 0: **ADON**: A/D On bit
1 = A/D converter module is operating
0 = A/D converter module is shutoff and consumes no operating current

11.2 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for all PIC MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

11.3 MPLAB C18 and MPLAB C30 C Compilers

The MPLAB C18 and MPLAB C30 Code Development Systems are complete ANSI C compilers for Microchip's PIC18 family of microcontrollers and dsPIC30F family of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

11.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

11.5 MPLAB ASM30 Assembler, Linker and Librarian

MPLAB ASM30 Assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

11.6 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, as well as internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C18 and MPLAB C30 C Compilers, and the MPASM and MPLAB ASM30 Assemblers. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent, economical software development tool.

12.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

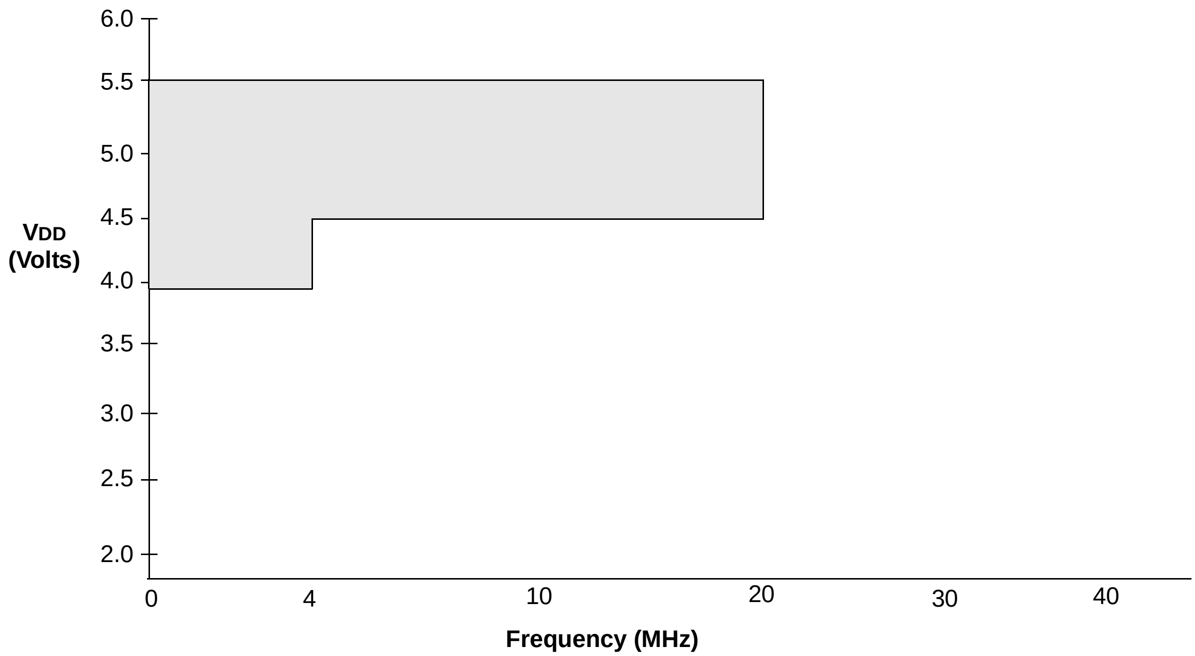
Ambient temperature under bias	-55°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$, and RA4)	-0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS}	-0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)**	0V to +13.25V
Voltage on RA4 with respect to Vss	0V to +8.5V
Total power dissipation **(Note 1)** (PDIP and SOIC)	1.0W
Total power dissipation **(Note 1)** (SSOP)	0.65W
Maximum current out of V_{SS} pin	300 mA
Maximum current into V_{DD} pin	250 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA and PORTB (combined)	200 mA
Maximum current sourced by PORTA and PORTB (combined)	200 mA

Note 1: Power dissipation is calculated as follows: $Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{Ol} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}$/V_{PP} pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{MCLR}$/V_{PP} pin rather than pulling this pin directly to V_{SS}.

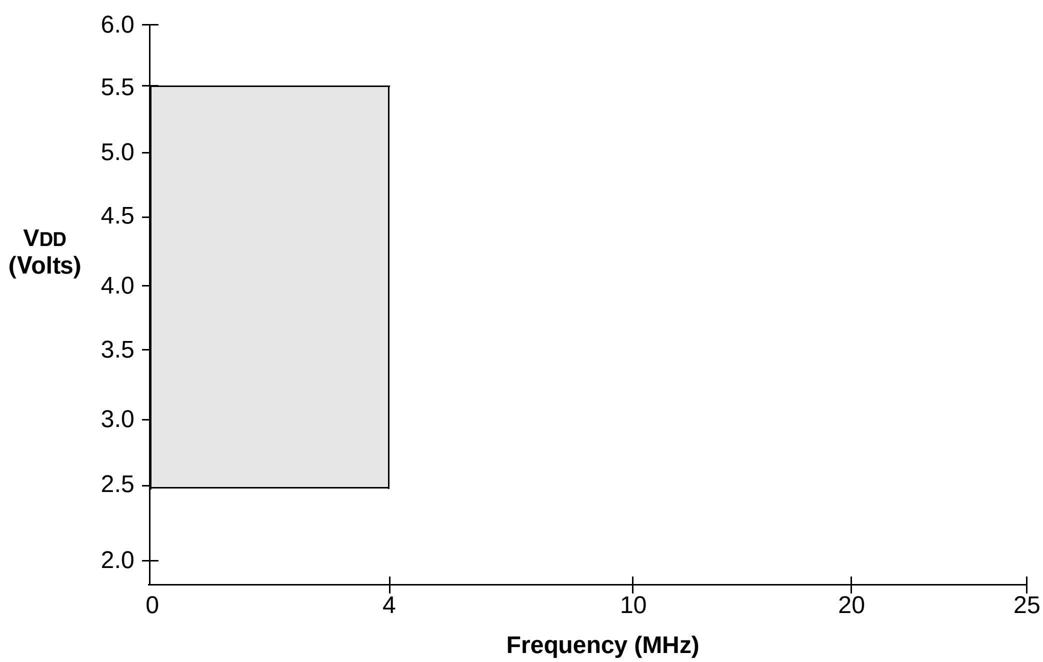
† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 12-1: PIC16C712/716 VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

FIGURE 12-2: PIC16LC712/716 VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

12.2 DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	2.5 VBOR*	— —	5.5 5.5	V V	 BOR enabled **(Note 7)**
D002*	VDR	**RAM Data Retention Voltage**(1)	—	1.5	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See section on Power-on Reset for details
D004* D004A*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05 TBD	— —	— —	V/ms	PWRT enabled ($\overline{\text{PWRTE}}$ bit clear) PWRT disabled ($\overline{\text{PWRTE}}$ bit set) See section on Power-on Reset for details
D005	VBOR	**Brown-out Reset** voltage trip point	3.65	—	4.35	V	BODEN bit set
D010 D010A	IDD	**Supply Current**(2,5)	— —	2.0 22.5	3.8 48	mA μA	XT, RC osc modes FOSC = 4 MHz, VDD = 3.0V **(Note 4)** LP osc mode FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020 D021 D021A	IPD	**Power-down Current**(3,5)	— — —	7.5 0.9 0.9	30 5 5	μA μA μA	VDD = 3.0V, WDT enabled, -40°C to +85°C VDD = 3.0V, WDT disabled, 0°C to +70°C VDD = 3.0V, WDT disabled, -40°C to +85°C
 D022* D022A*	 ΔIWDT ΔIBOR	**Module Differential Current**(6) Watchdog Timer Brown-out Reset	 — —	 6.0 TBD	 20 200	 μA μA	 WDTE bit set, VDD = 4.0V BODEN bit set, VDD = 5.0V
1A	FOSC	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	KHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

4: For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ T_A ≤ +70°C for commercial -40°C ≤ T_A ≤ +85°C for industrial -40°C ≤ T_A ≤ +125°C for extended Operating voltage V_{DD} range as described in DC spec **Section 12.1 "DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)"** and **Section 12.2 "DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)"**				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
		Output Low Voltage					
D080	V_{OL}	I/O ports	—	—	0.6	V	I_{OL} = 8.5 mA, V_{DD} = 4.5V, -40°C to +85°C
			—	—	0.6	V	I_{OL} = 7.0 mA, V_{DD} = 4.5V, -40°C to +125°C
D083		OSC2/CLKOUT (RC Osc mode)	—	—	0.6	V	I_{OL} = 1.6 mA, V_{DD} = 4.5V, -40°C to +85°C
			—	—	0.6	V	I_{OL} = 1.2 mA, V_{DD} = 4.5V, -40°C to +125°C
		Output High Voltage					
D090	V_{OH}	I/O ports **(Note 3)**	V_{DD}-0.7	—	—	V	I_{OH} = -3.0 mA, V_{DD} = 4.5V, -40°C to +85°C
			V_{DD}-0.7	—	—	V	I_{OH} = -2.5 mA, V_{DD} = 4.5V, -40°C to +125°C
D092		OSC2/CLKOUT (RC Osc mode)	V_{DD}-0.7	—	—	V	I_{OH} = -1.3 mA, V_{DD} = 4.5V, -40°C to +85°C
			V_{DD}-0.7	—	—	V	I_{OH} = -1.0 mA, V_{DD} = 4.5V, -40°C to +125°C
D150*	V_{OD}	**Open-Drain High Voltage**	—	—	8.5	V	RA4 pin
		Capacitive Loading Specs on Output Pins					
D100	C_{OSC2}	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	C_{IO}	All I/O pins and OSC2 (in RC mode)	—	—	50	pF	

* These parameters are characterized but not tested.

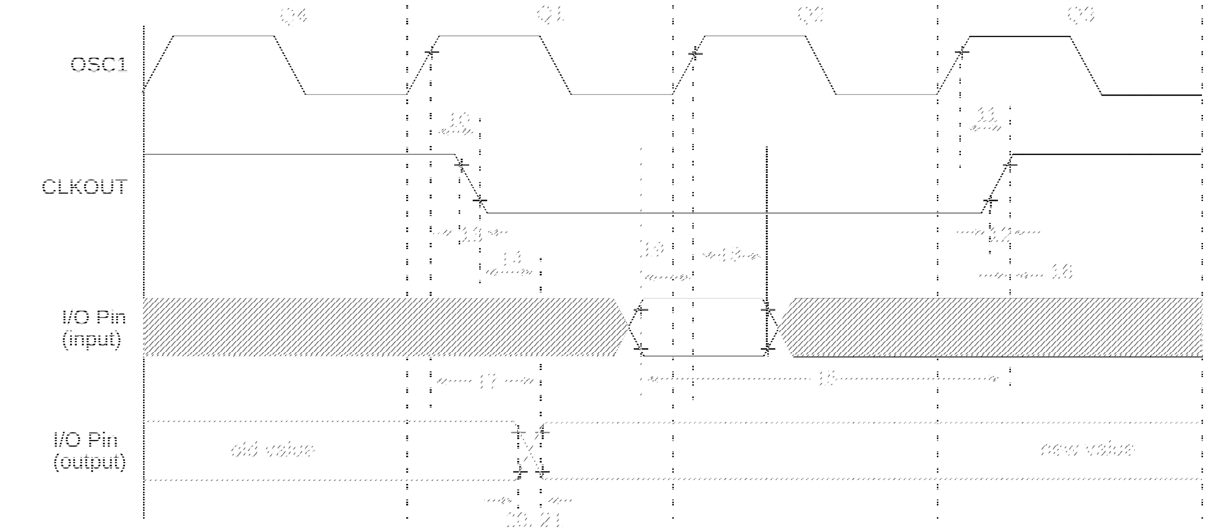
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC Oscillator mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC MCU be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$/V_{PP} pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 12-5: CLKOUT AND I/O TIMING



Note: Refer to Figure 12-3 for load conditions.

TABLE 12-3: CLKOUT AND I/O TIMING REQUIREMENTS

Param No.	Sym.	Characteristic		Min.	Typ†	Max.	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		—	75	200	ns	**Note 1**
11*	TosH2ckH	OSC1¦ to CLKOUT¦		—	75	200	ns	**Note 1**
12*	TckR	CLKOUT rise time		—	35	100	ns	**Note 1**
13*	TckF	CLKOUT fall time		—	35	100	ns	**Note 1**
14*	TckL2ioV	CLKOUT Ø to Port out valid		—	—	0.5TCY + 20	ns	**Note 1**
15*	TioV2ckH	Port in valid before CLKOUT ¦		Tosc + 200	—	—	ns	**Note 1**
16*	TckH2ioI	Port in hold after CLKOUT ¦		0	—	—	ns	**Note 1**
17*	TosH2ioV	OSC1¦ (Q1 cycle) to Port out valid		—	50	150	ns	
18*	TosH2ioI	OSC1¦ (Q2 cycle) to Port input invalid (I/O in hold time)	Standard	100	—	—	ns	
18A*			Extended (LC)	200	—	—	ns	
19*	TioV2osH	Port input valid to OSC1¦ (I/O in setup time)		0	—	—	ns	
20*	TioR	Port output rise time	Standard	—	10	40	ns	
20A*			Extended (LC)	—	—	80	ns	
21*	TioF	Port output fall time	Standard	—	10	40	ns	
21A*			Extended (LC)	—	—	80	ns	
22††*	TINP	INT pin high or low time		TCY	—	—	ns	
23††*	TRBP	RB7:RB4 change INT high or low time		TCY	—	—	ns	

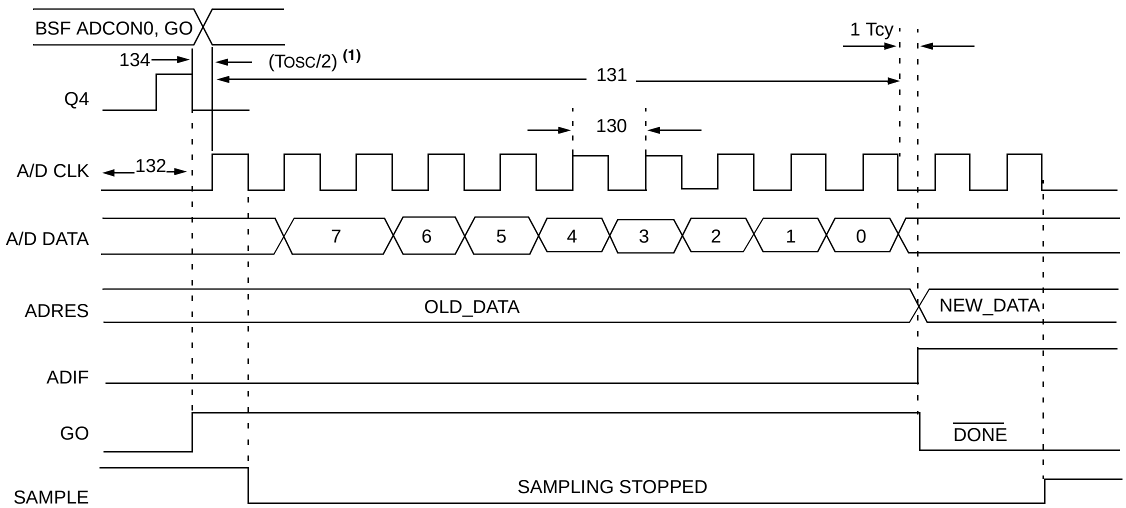
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edge.

Note1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

FIGURE 12-10: A/D CONVERSION TIMING



Note1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 12-8: A/D CONVERSION REQUIREMENTS

Param No.	Sym.	Characteristic		Min.	Typ†	Max.	Units	Conditions
130	TAD	A/D clock period	Standard	1.6	—	—	µs	TOSC based, VREF ≥ 3.0V
			Extended (LC)	2.0	—	—	µs	TOSC based, VREF full range
			Standard	2.0	4.0	6.0	µs	A/D RC Mode
			Extended (LC)	3.0	6.0	9.0	µs	A/D RC Mode
131	TCNV	Conversion time (not including S/H time) **(Note 1)**		11	—	11	TAD	
132	TACQ	Acquisition time		**(Note 2)**	20	—	µs	
				5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the “new” input voltage has not changed by more than 1 LSb (i.e., 20.0 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
134	TGO	Q4 to A/D clock start		—	TOSC/2 §	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.
135	TSWC	Switching from convert Æ sample time		1.5 §	—	—	TAD	

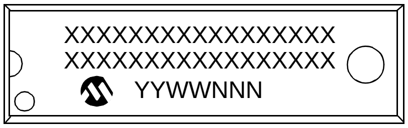
: * These parameters are characterized but not tested.
: † Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
: § This specification ensured by design.

Note 1: ADRES register may be read on the following TCY cycle.
2: See **Section 9.1 “Configuration Bits”** for min. conditions.

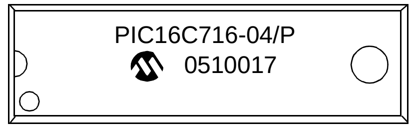
13.0 PACKAGING INFORMATION

13.1 Package Marking Information

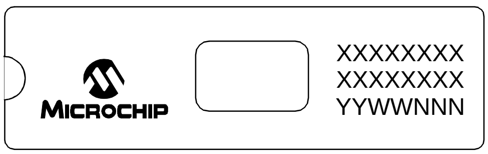
18-Lead PDIP



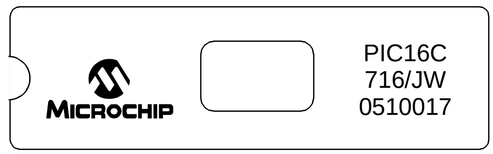
Example



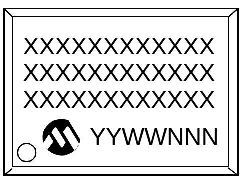
18-Lead CERDIP Windowed



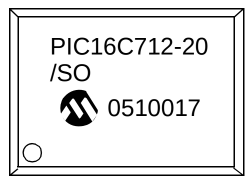
Example



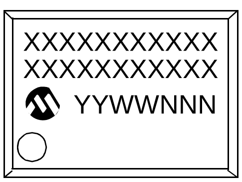
18-Lead SOIC (.300”)



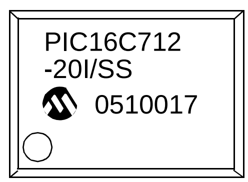
Example



20-Lead SSOP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

Q

R

S

T

W